

# Detector Developments for the European XFEL.

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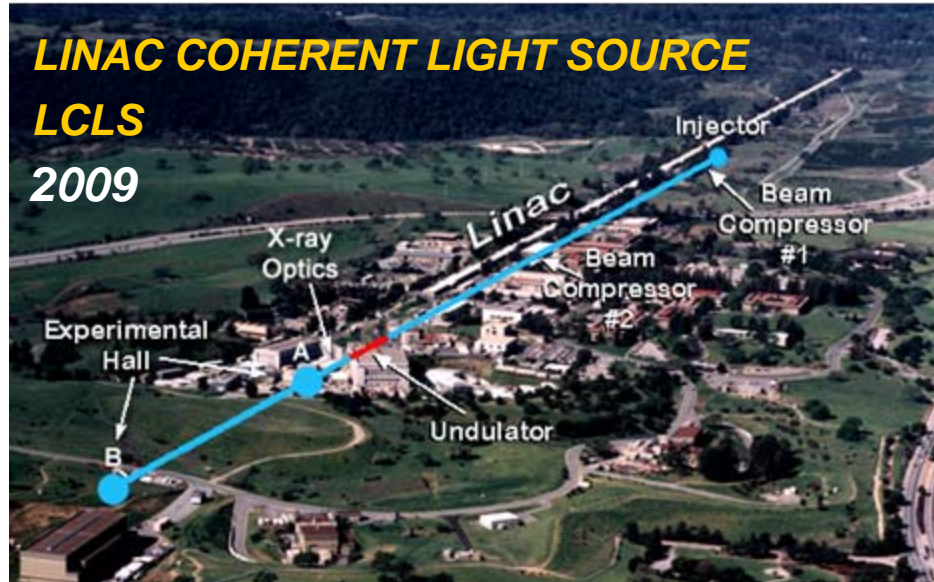
**4<sup>th</sup> Detector Workshop of the Helmholtz Alliance;  
March 2011**

- **The FEL Detector Challenge**
- **The AGIPD project**
- **The DSSC project**
- **Summary / Conclusions**





# FEL Sources in the world



**FLASH:** 5 Hz, 10 Hz  
and 5 MHz

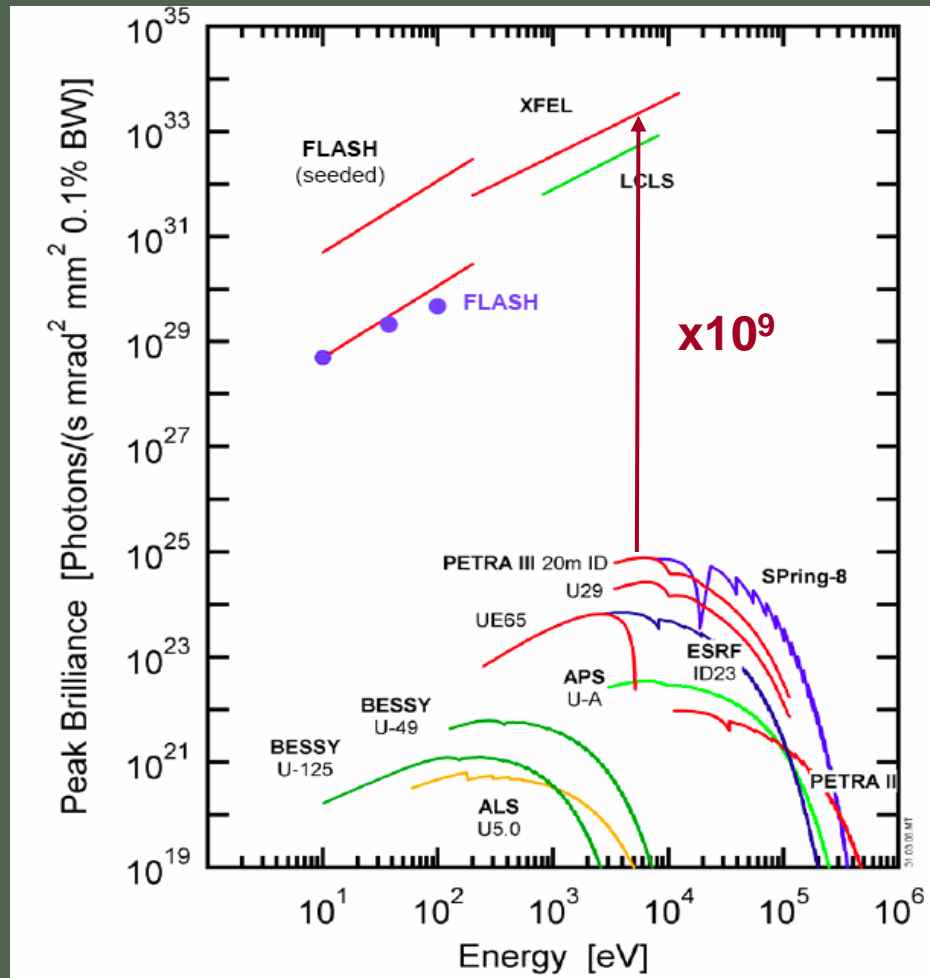
**LCLS:** 120 Hz

**SCSS:** 60 Hz

**XFEL:** 5 Hz, 10 Hz  
and 5 MHz

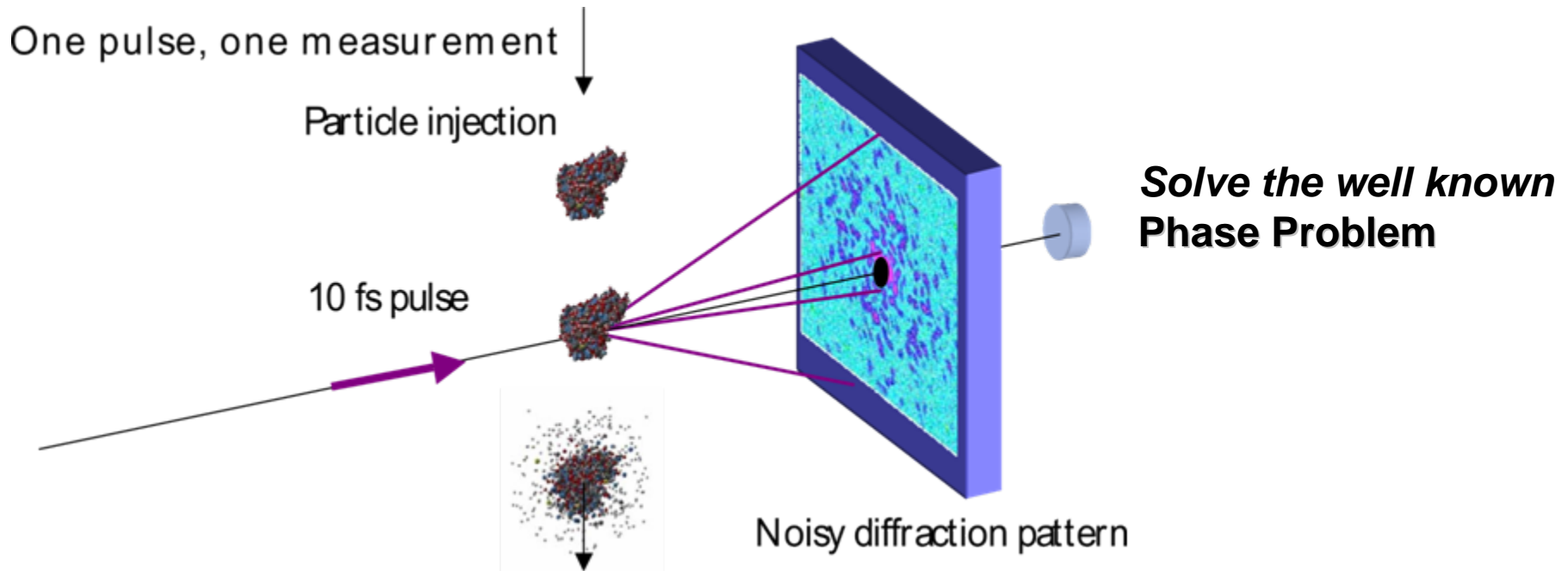


# Challenge: Different Science

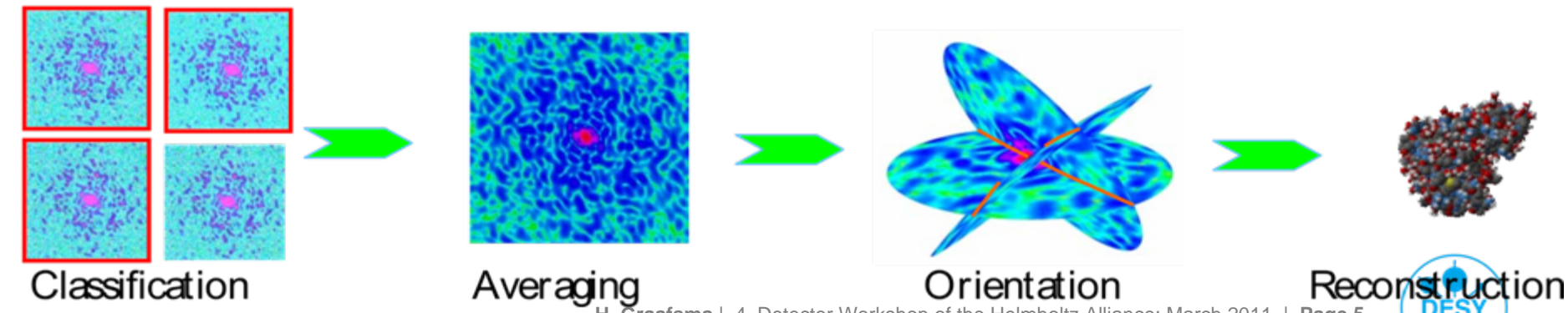


- Completely new science
- Fast science 100 fsec
- “Single shot” science

# Single shot experiments



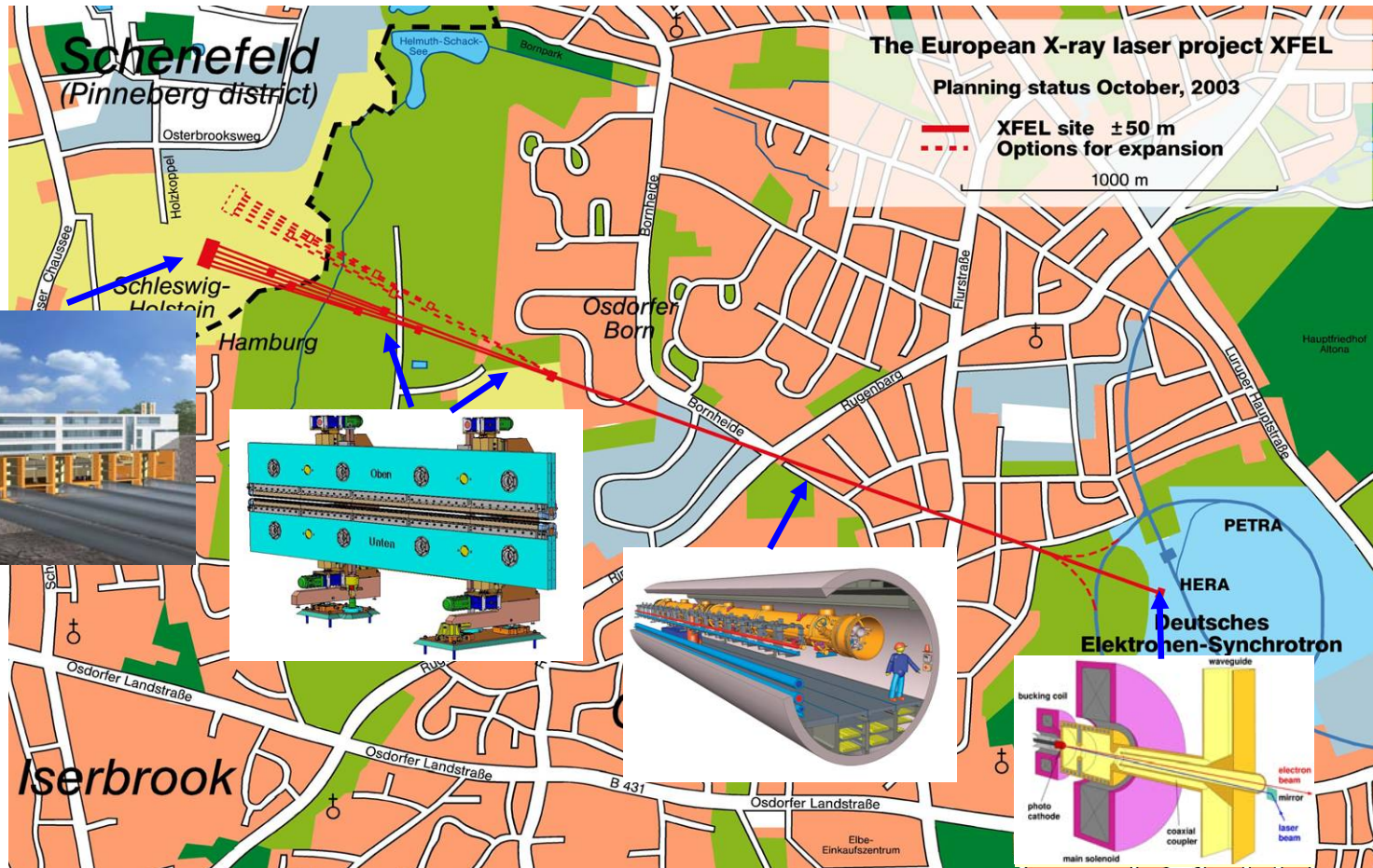
Combine  $10^5 - 10^7$  measurements





# Overall layout of the European XFEL

← 3.4km →

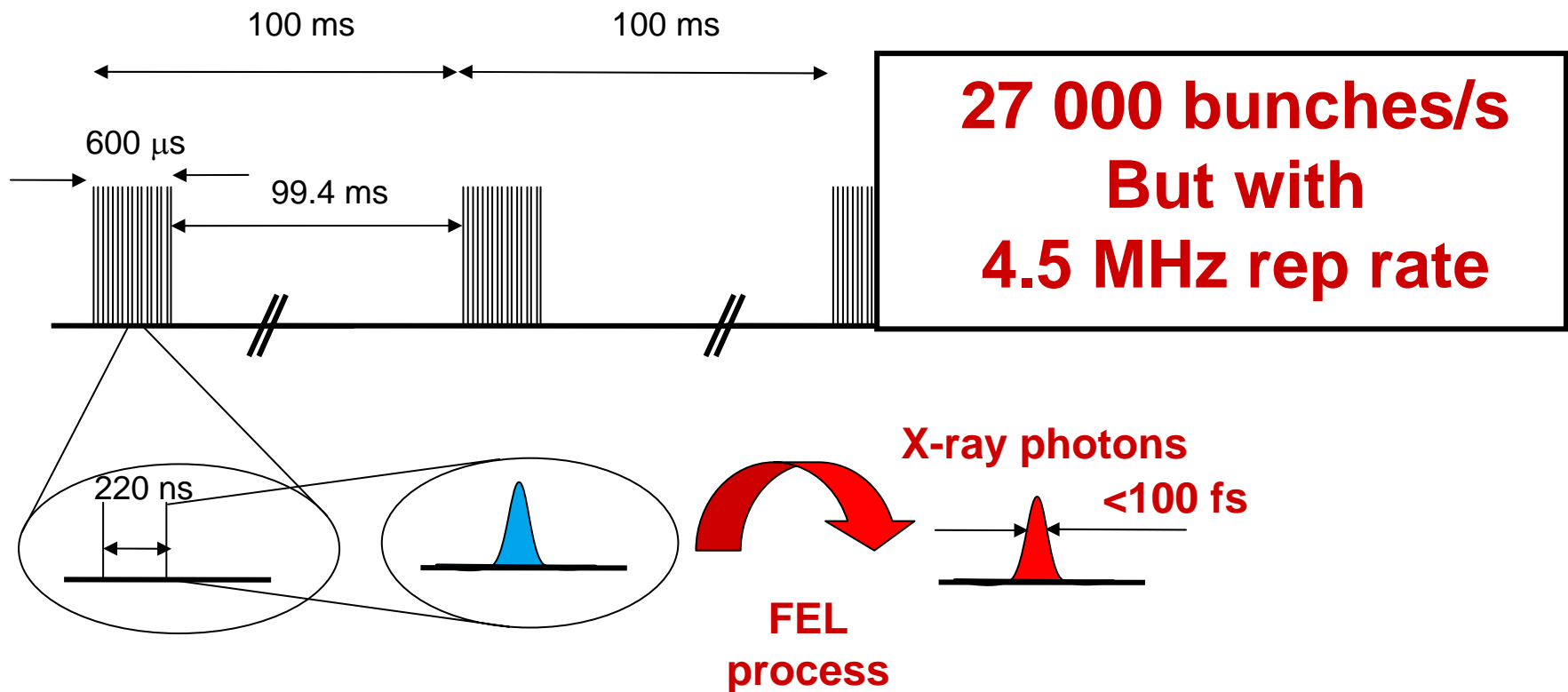


# XFEL experiment complex at Schenefeld site



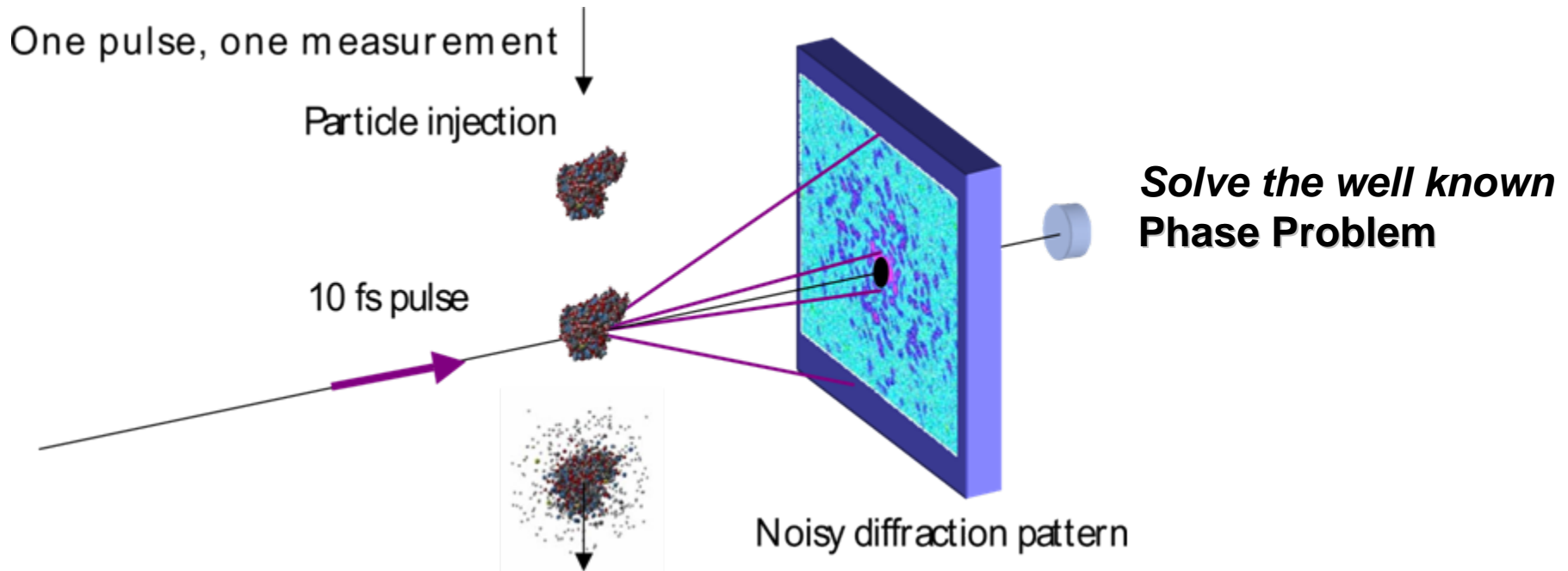
# E-XFEL Challenge: Time structure = difference with “others”

Electron bunch trains; up to 2700 bunches in 600  $\mu\text{s}$ , repeated 10 times per second.  
Producing 100 fsec X-ray pulses (up to 27 000 bunches per second).

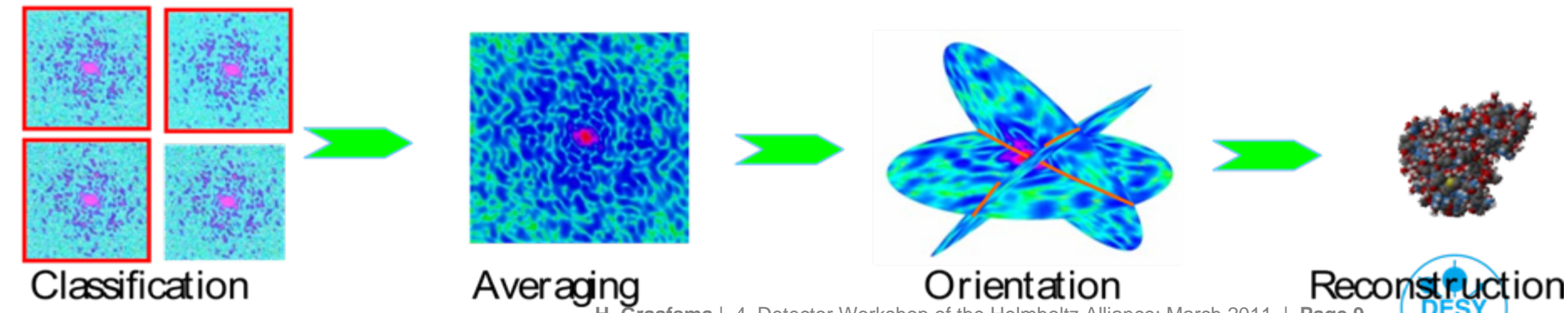




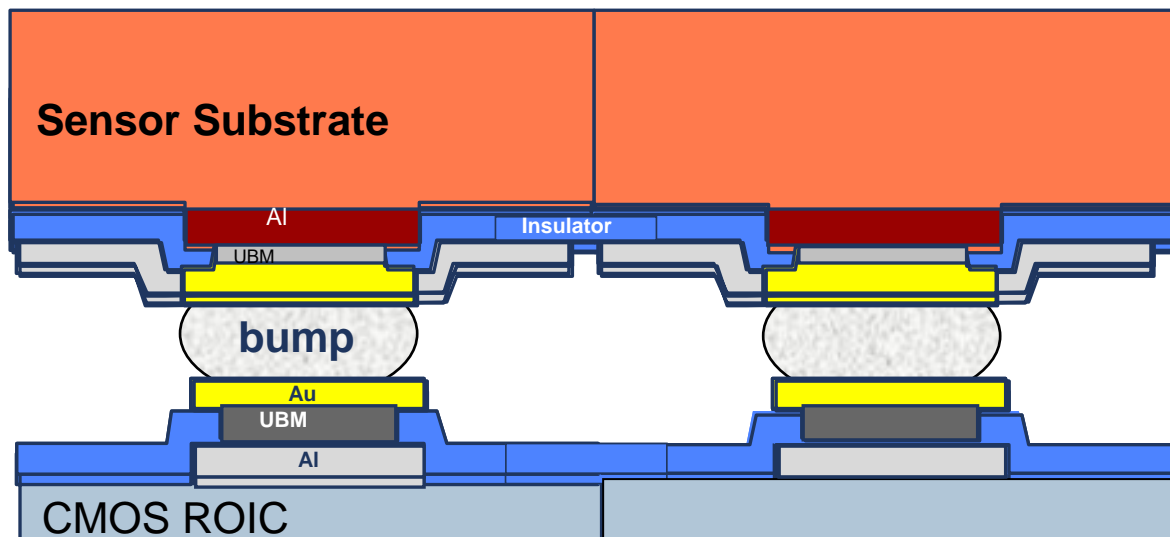
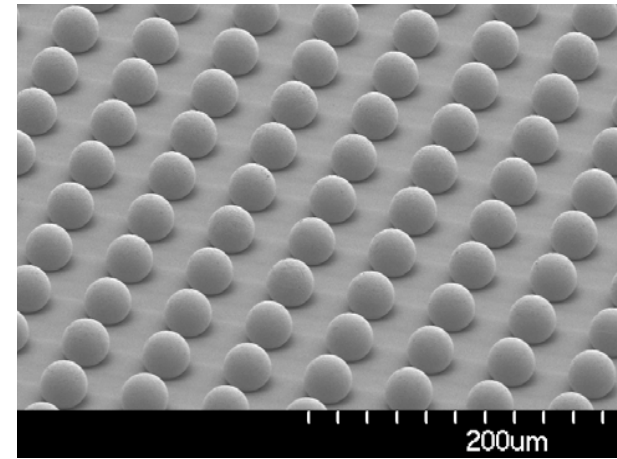
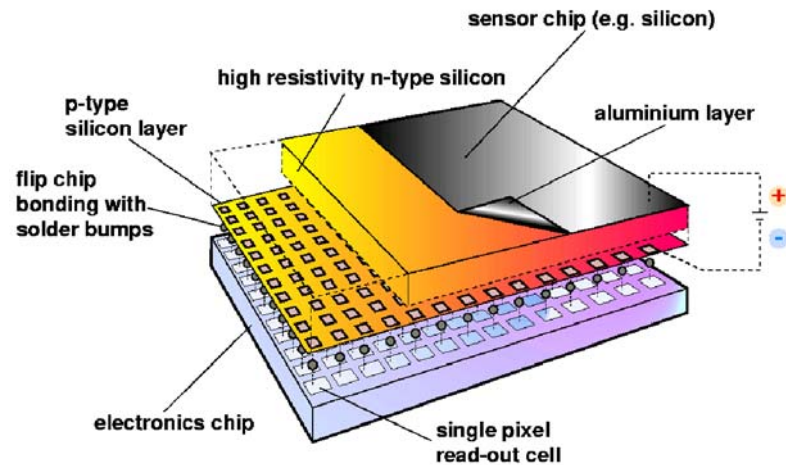
# Single shot experiments



Combine  $10^5 - 10^7$  measurements



# Hybrid Pixel Technology



# The **A**daptive **G**ain **I**ntegrating **P**ixel **D**etector (**AGIPD**) project





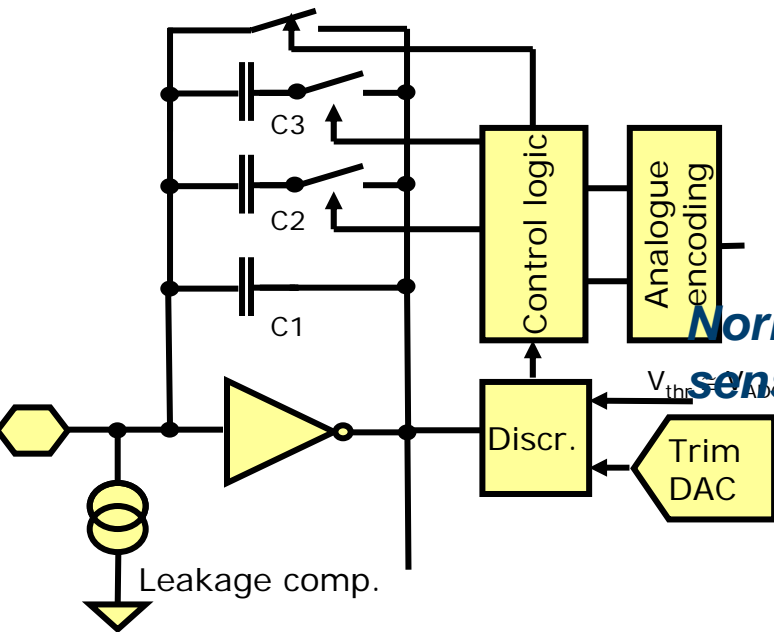
# The Adaptive Gain Integrating Pixel Detector

*High dynamic range:*

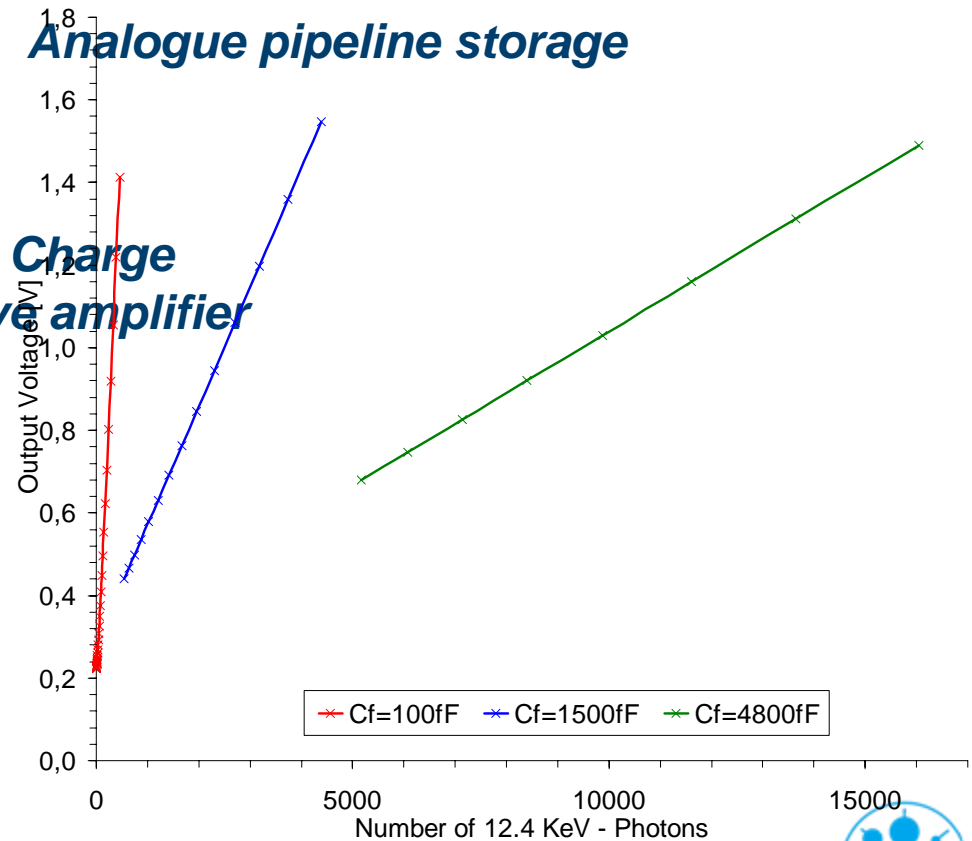
*Dynamically gain switching system*

*Extremely fast readout (200ns):*

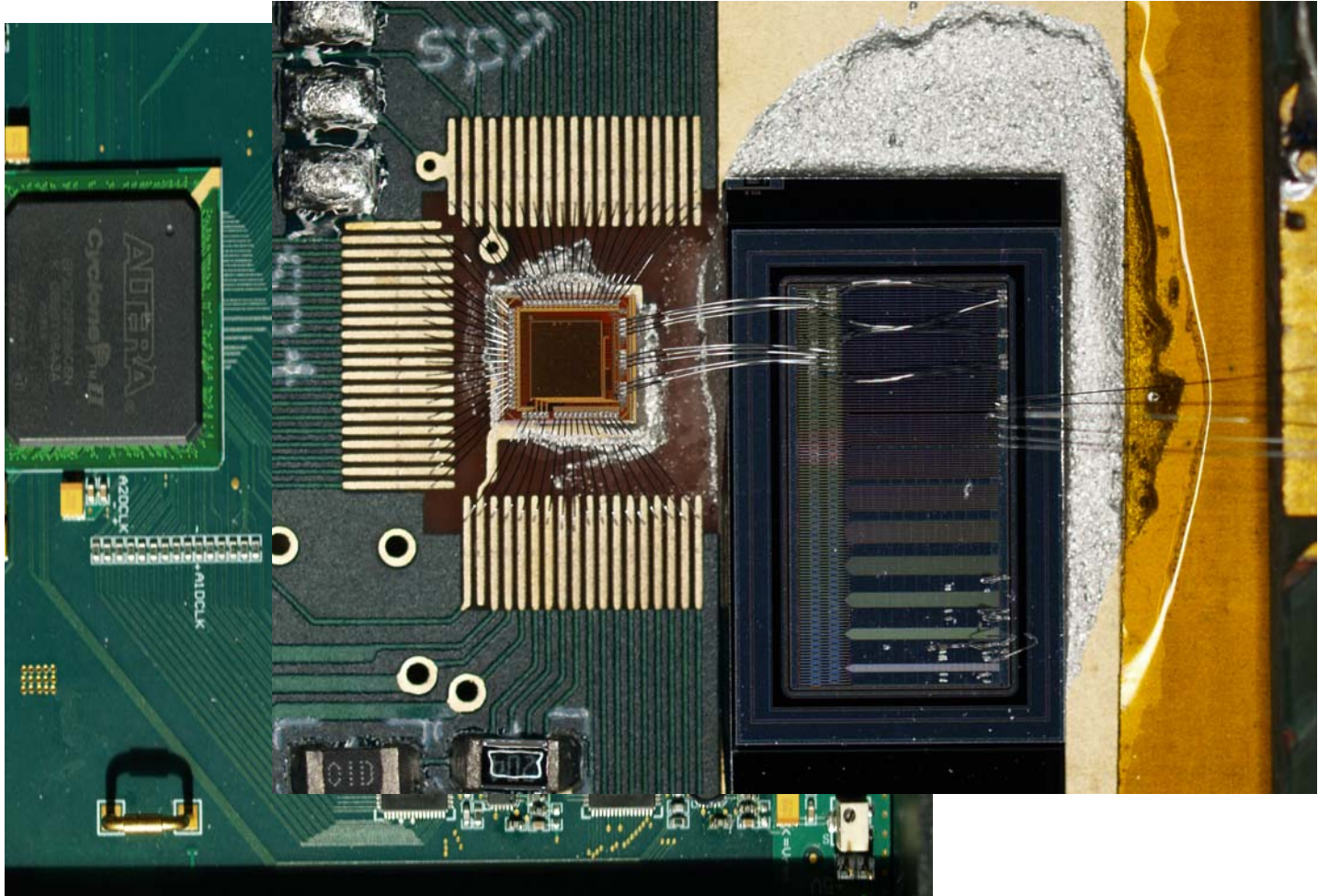
*Analogue pipeline storage*



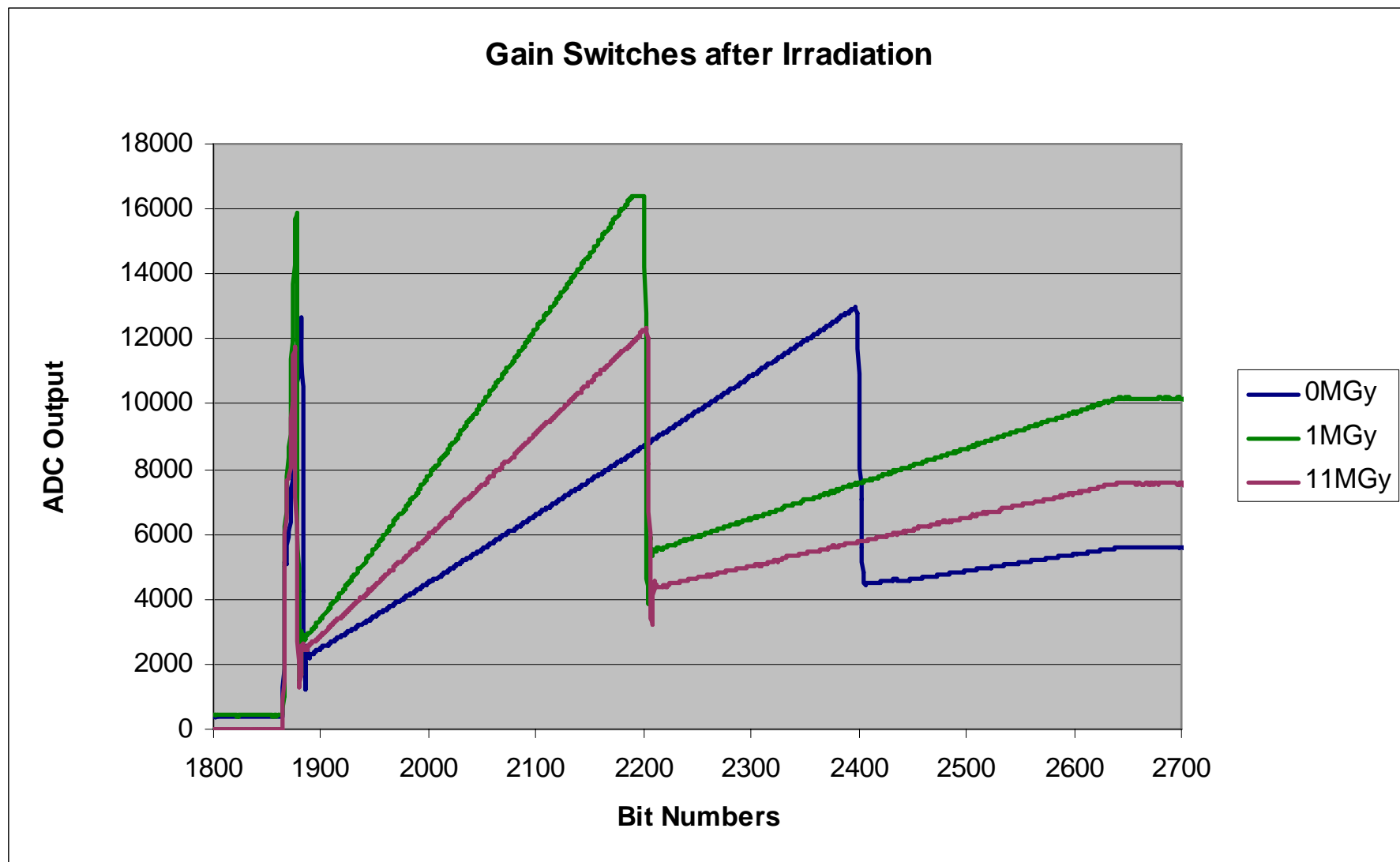
*Normal Charge sensitive amplifier*



# Overview of the chip test board



# Dynamic Gain Switching works!





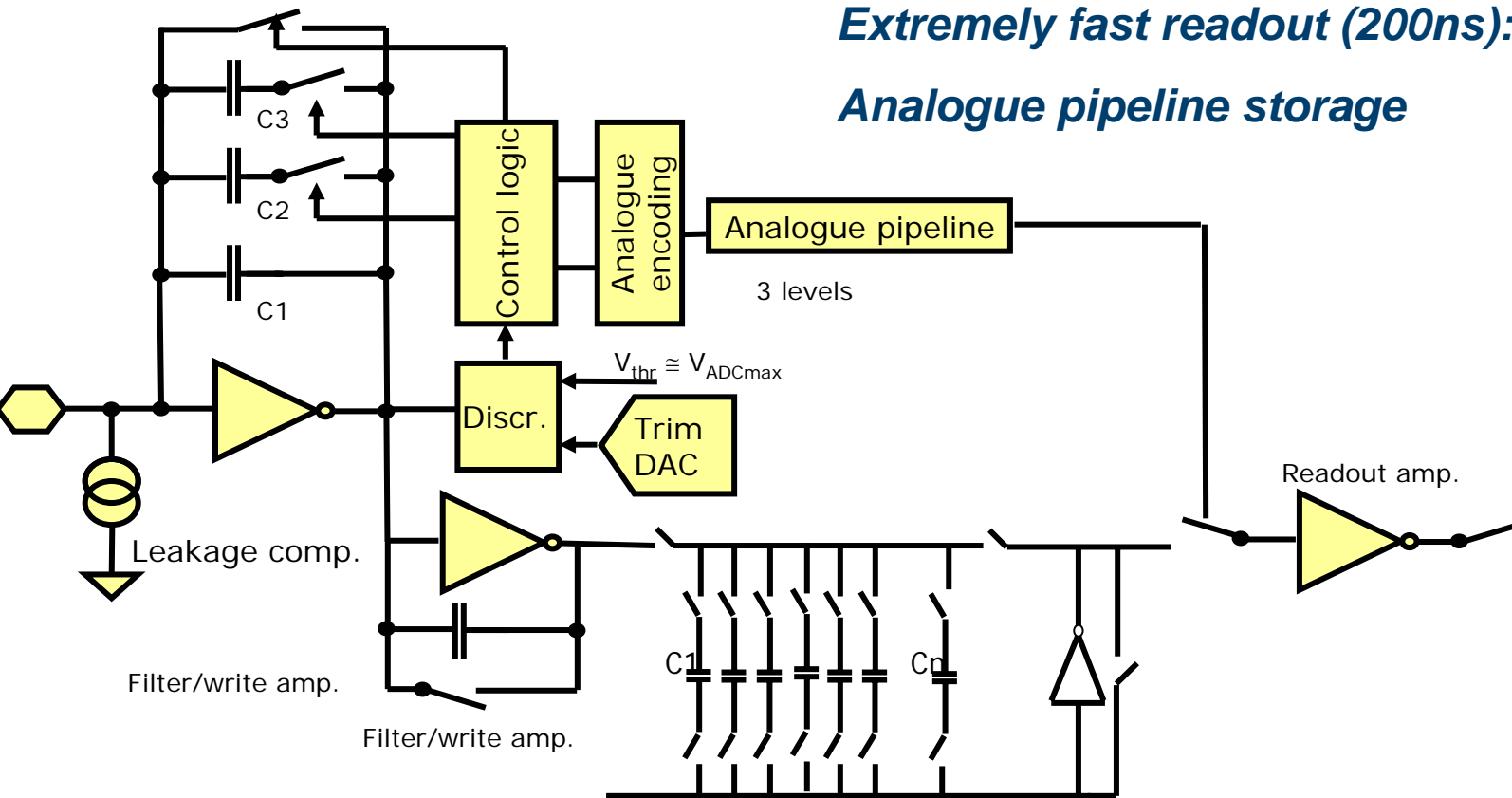
# The Adaptive Gain Integrating Pixel Detector

*High dynamic range:*

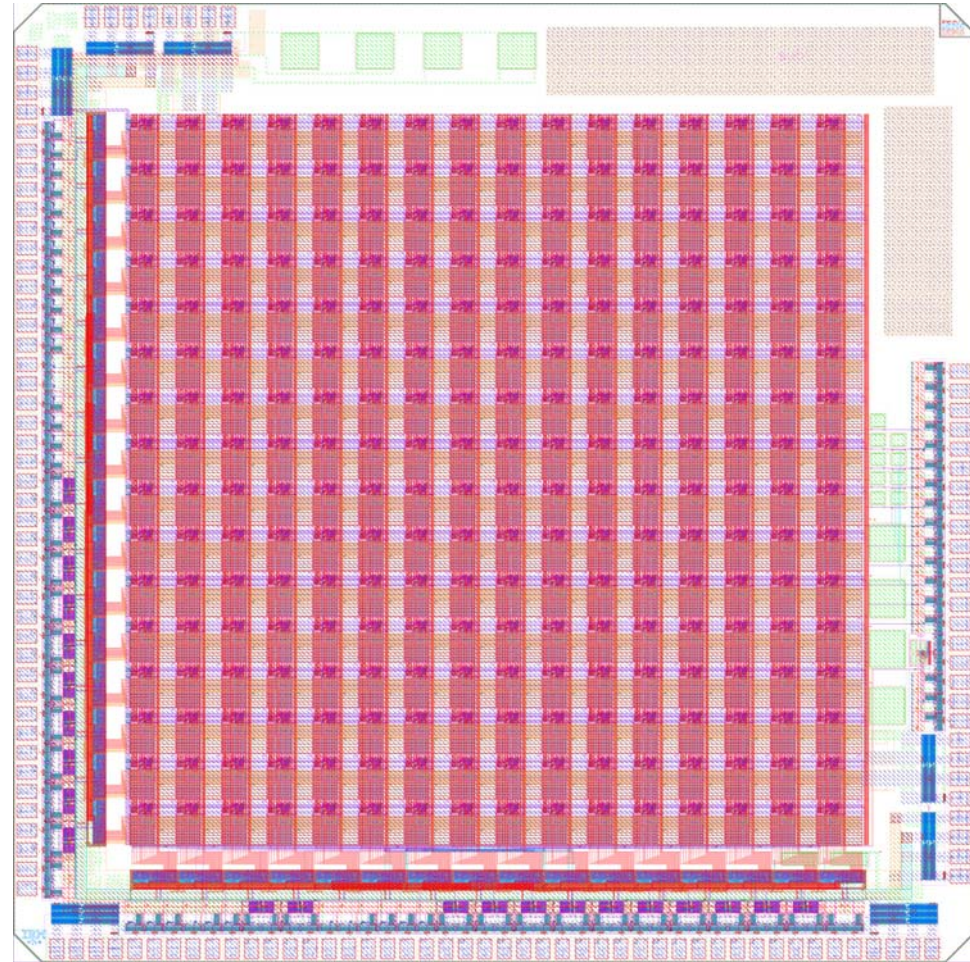
*Dynamically gain switching system*

*Extremely fast readout (200ns):*

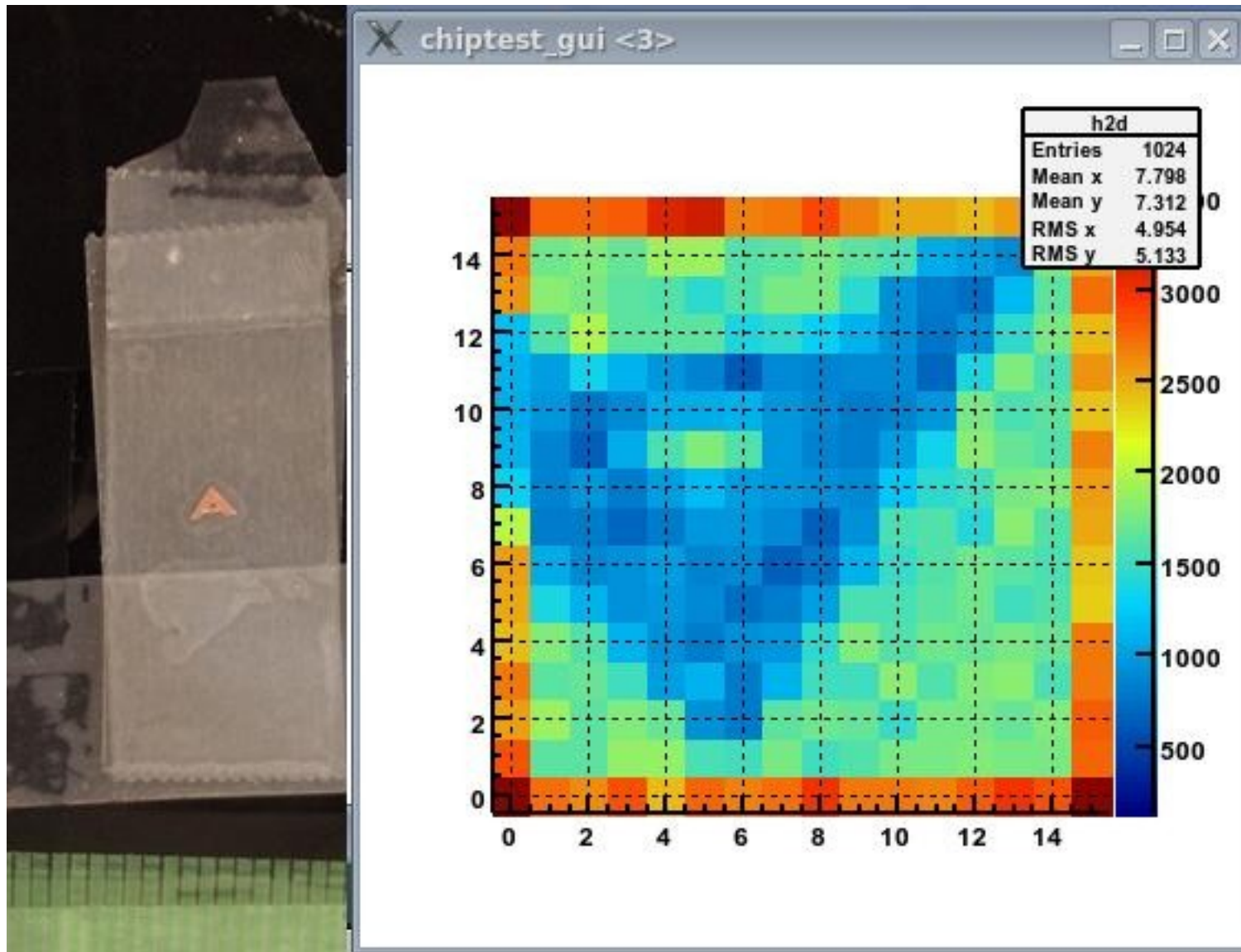
*Analogue pipeline storage*



- 16 x 16 pixel prototype
- Adaptive gain
- Different flavors of storage
- 100 frames per pixel

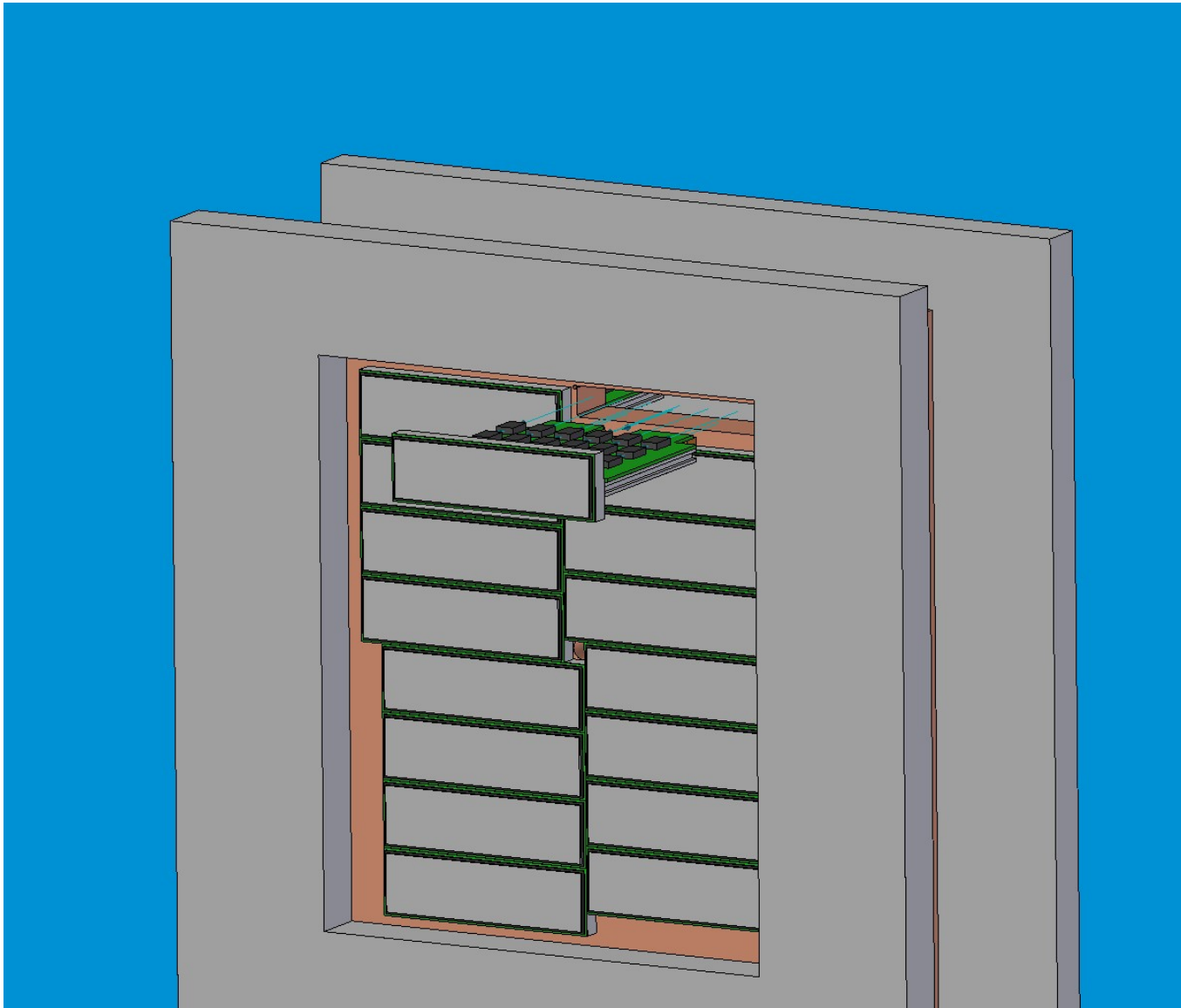


# First X-ray image taken with AGIPD02





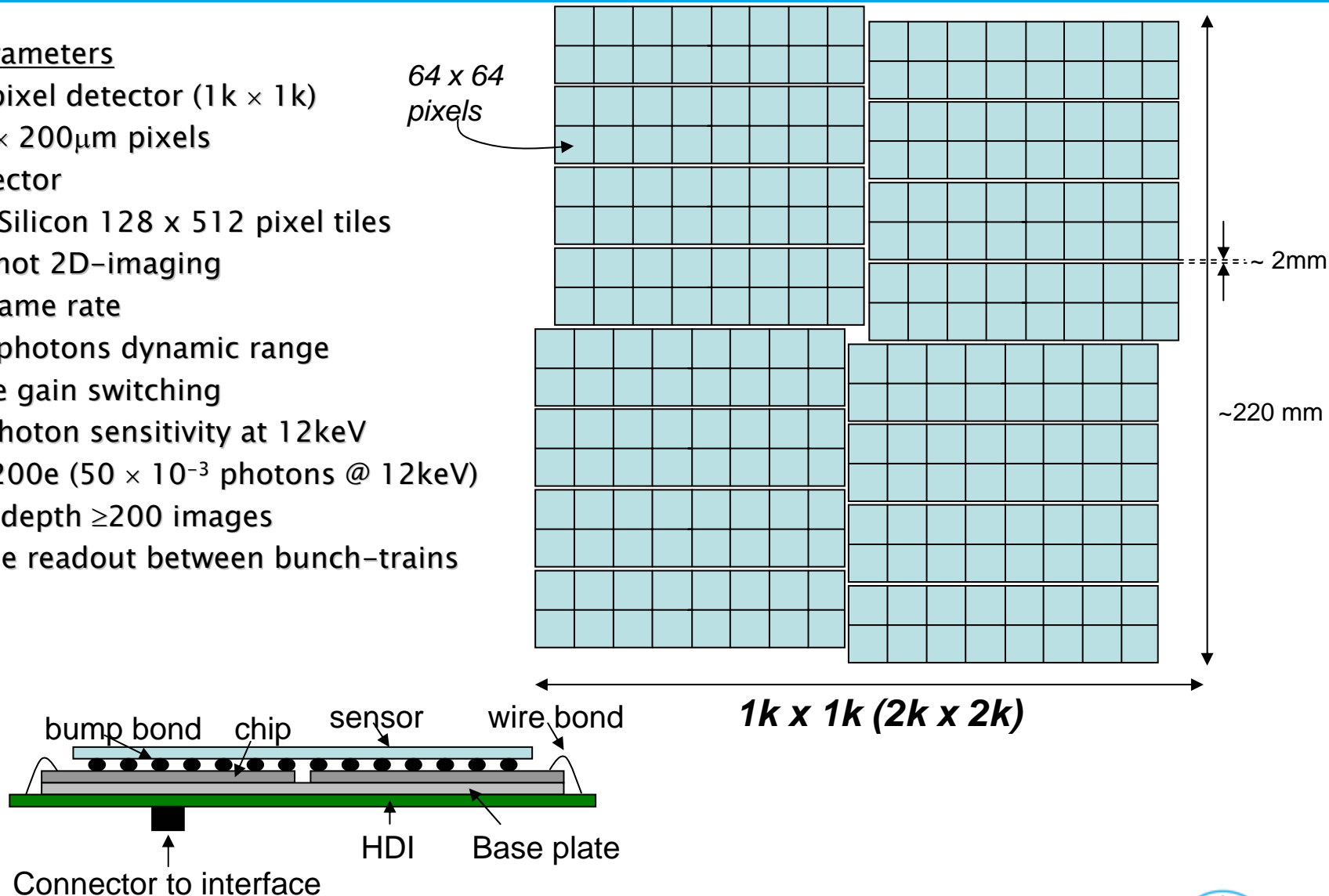
# The 1k x 1k detector



# The Adaptive Gain Integrating Pixel Detector

## Basic parameters

- 1 Megapixel detector ( $1k \times 1k$ )
- $200\mu m \times 200\mu m$  pixels
- Flat detector
- Sensor: Silicon  $128 \times 512$  pixel tiles
- Single shot 2D-imaging
- 5MHz frame rate
- $2 \times 10^4$  photons dynamic range
- Adaptive gain switching
- Single photon sensitivity at 12keV
- Noise  $\leq 200e$  ( $50 \times 10^{-3}$  photons @ 12keV)
- Storage depth  $\geq 200$  images
- Analogue readout between bunch-trains



# The Adaptive Gain Integrating Pixel Detector

## > The AGIPD consortium:

PSI/SLS -Villingen: chip design; interconnect and module assembly

Universität Bonn: chip design

Universität Hamburg: radiation damage tests, “charge explosion” studies; and sensor design

DESY: chip design, interface and control electronics, mechanics, cooling; overall coordination

## Some Facts

5 years development

~ 20 people

## Some Milestones

First 16x16 pixels prototype

End 2010

Definition of final design

Summer 2011

Production, assembly and test

>2013



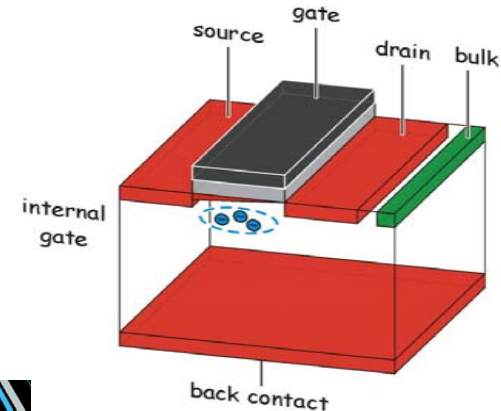


# The **DE**PFET **S**ensor with **S**ignal **C**ompression (DSSC)



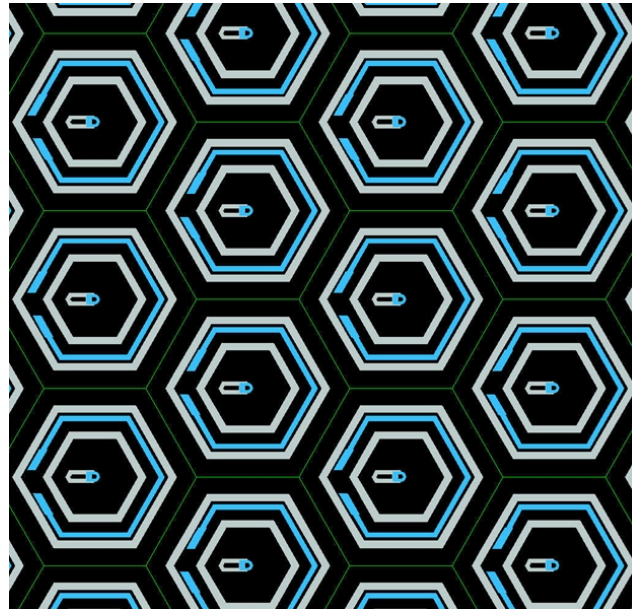
# DSSC - DEPMOS Sensor with Signal Compression

- > DEPFET per pixel
- > Very low noise (good for soft X-rays)
- > non linear gain (good for dynamic range)
- > per pixel ADC
- > digital storage pipeline



- > **Hexagonal pixels**  
**200 $\mu$ m pitch**

- combines DEPFET
- with small area drift detector (scaleable)

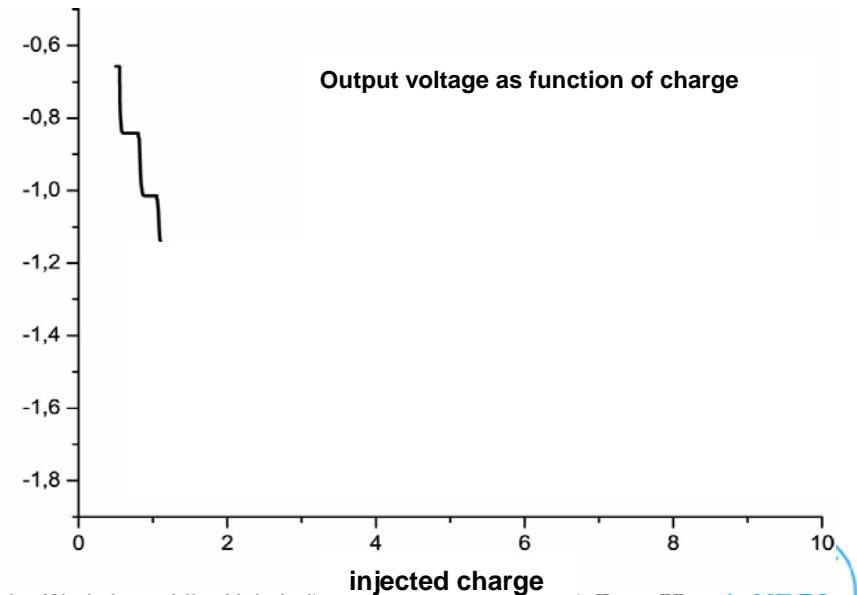
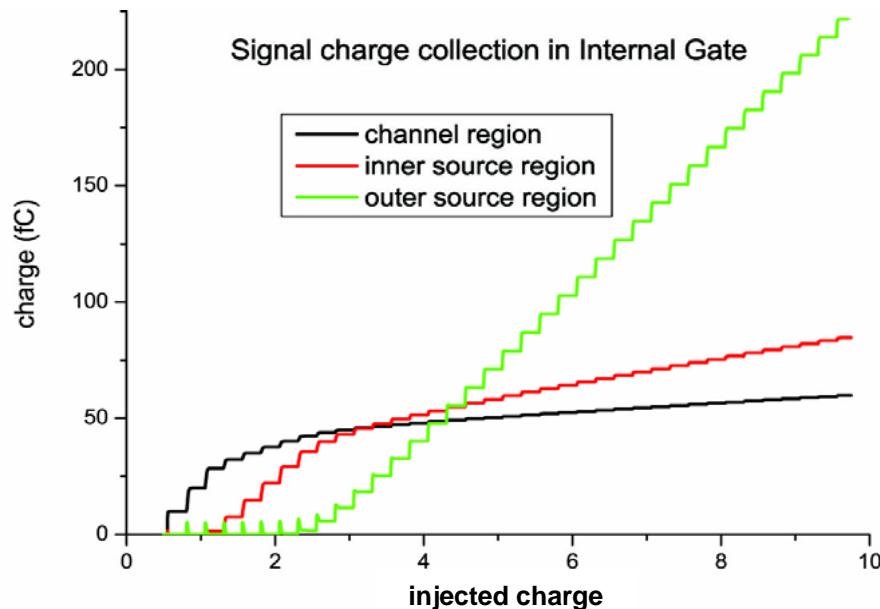
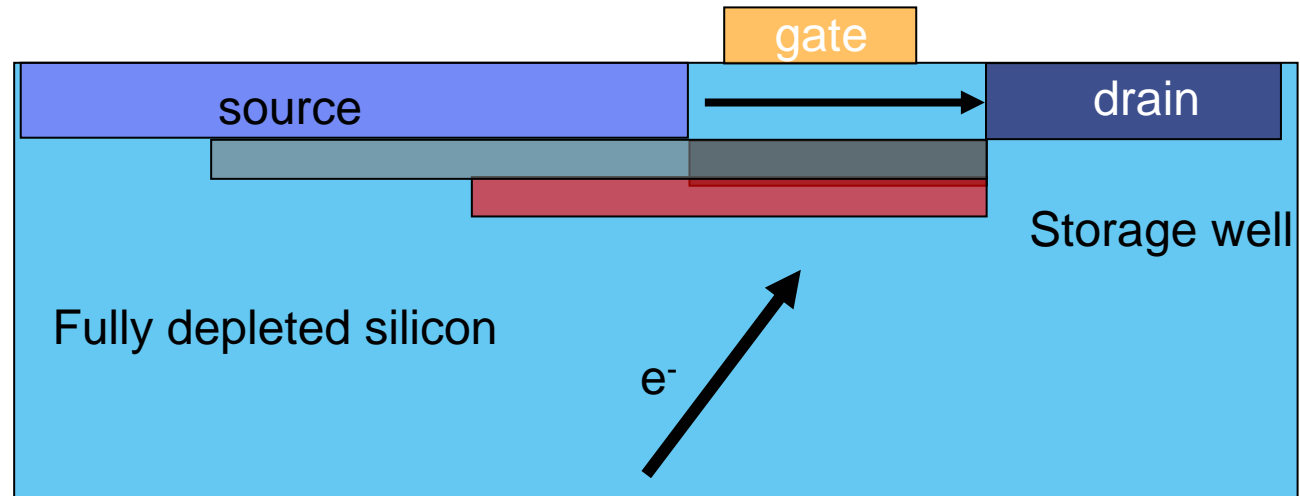
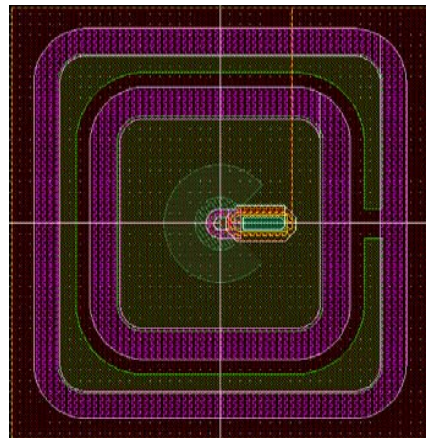


- > MPI-HLL, Munich
- > Universität Heidelberg
- > Universität Siegen
- > Politecnico di Milano
- > Università di Bergamo
- > DESY, Hamburg

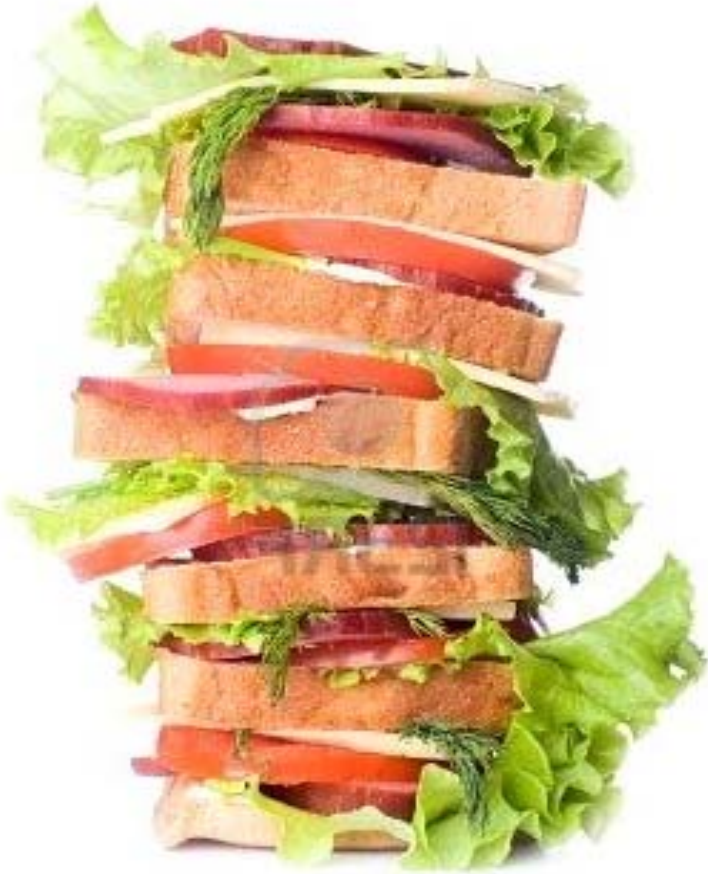
# DEPMOS Sensor with Signal Compression

**DEPFET:** Electrons are collected in a storage well

⇒ Influence current from source to drain



## why to go vertical

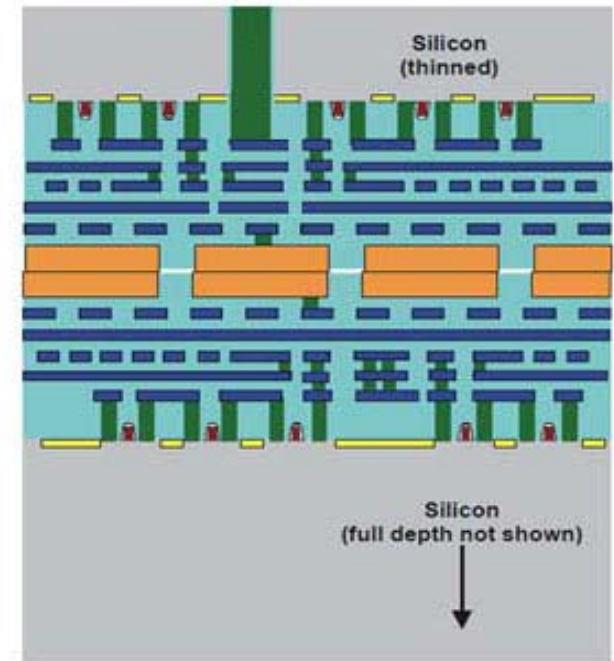
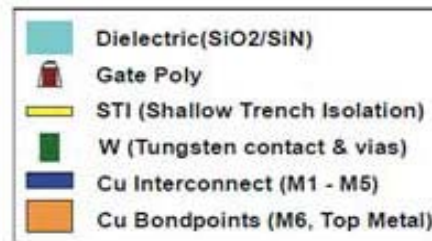


- > Increased effective area
  - cheating on the area constraint
- > better I/O connections
  - shorter, faster, and more of them
- > integration of different technologies
  - select the most suitable tech to do each thing



# going vertical: a simple AGIPD evolution hypothesis

- > Chartered-Tezzaron technology
- > CMOS Low Power, 130 nm , 1.5 V
- > available for MPW through MOSIS



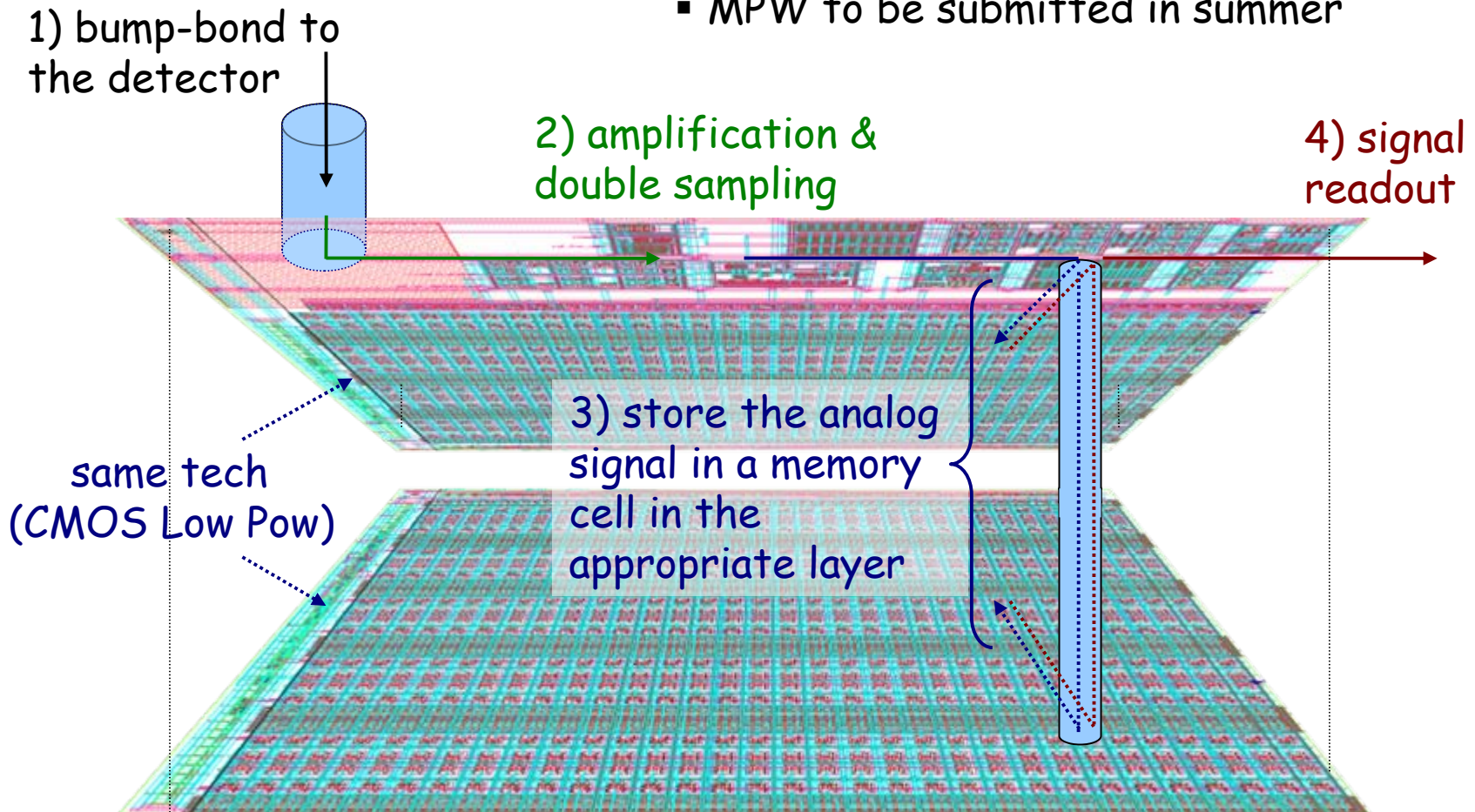
## other hypothesis

- > Ziptronix (3D bonding only)
- > Fraunhofer (TSV only)
- > IMEC (developing)
- > AMS (developed but not commercially available yet)
- > IBM (TSV not insulated yet)
- > 3D Package (Amkor, Tessera)

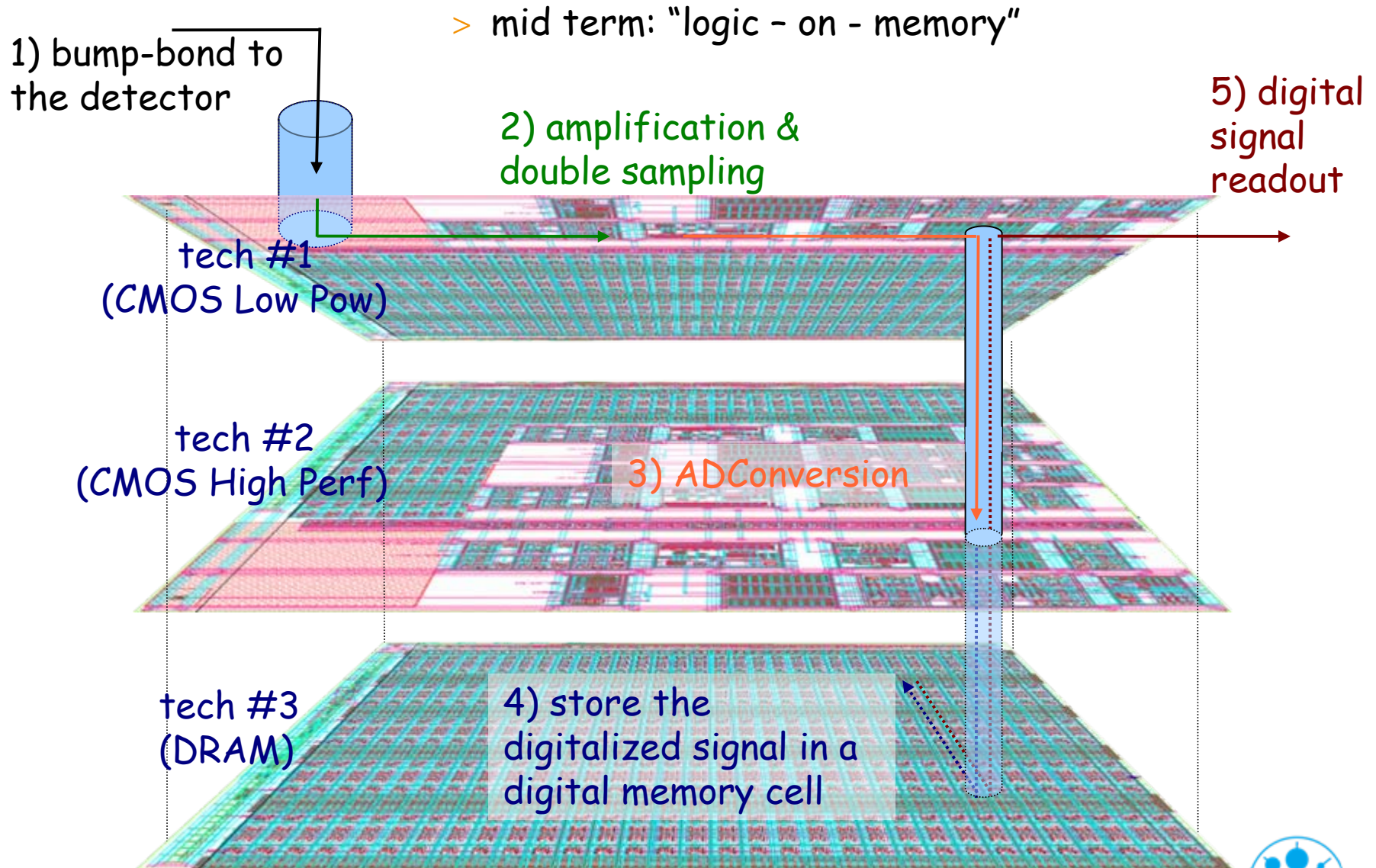
# going vertical: a simple AGIPD evolution hypothesis

> near future: "logic - on - logic"

▪ MPW to be submitted in summer



## going vertical: a simple AGIPD evolution hypothesis





# Summary

- > FELs need conceptually new detectors: fast, low noise, large dynamic range
- > Dedicated detector developments for Photon Science (Europe, Japan and USA)
- > Detectors will be decisive for the success of the European XFEL (bunch train structure).
- > Photon Science possibly driving force for new detector developments, but synergy with HEP essential.

